

General Description

The 87946I-147 is a low skew, $\div 1$, $\div 2$ LVC MOS/LVTTL Fanout Buffer. The 87946I-147 has two selectable single ended clock inputs. The single ended clock inputs accept LVC MOS or LVTTL input levels. The low impedance LVC MOS/LVTTL outputs are designed to drive 50 Ω series or parallel terminated transmission lines. The effective fanout can be increased from 10 to 20 by utilizing the ability of the outputs to drive two series terminated lines.

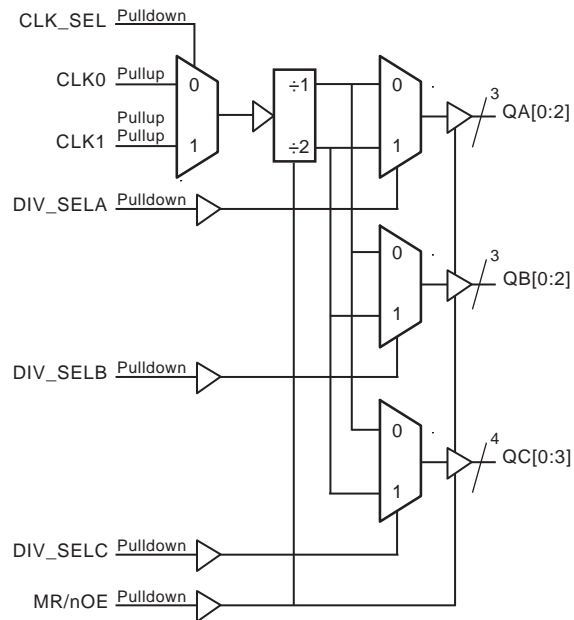
The divide select inputs, DIV_SELx, control the output frequency of each bank. The outputs can be utilized in the $\div 1$, $\div 2$ or a combination of $\div 1$ and $\div 2$ modes. The master reset input, MR/nOE, resets the internal frequency dividers and also controls the active and high impedance states of all outputs.

The 879461-147 is characterized at full 3.3V for input V_{DD} , and mixed 3.3V and 2.5V for output operating supply mode. Guaranteed bank, output and part-to-part skew characteristics make the 879461-147 ideal for those clock distribution applications demanding well defined performance and repeatability.

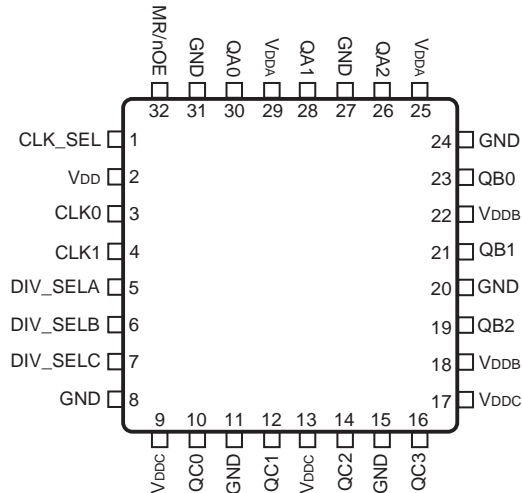
Features

- Ten single ended LVCMOS/LVTTL outputs, 7Ω typical output impedance
- Selectable LVCMOS/LVTTL CLK0 and CLK1 inputs
- CLK0 and CLK1 can accept the following input levels: LVCMOS and LVTTL
- Maximum input frequency: 250MHz
- Bank skew: 30ps (maximum)
- Output skew: 175ps (maximum)
- Part-to-part skew: 850ps (maximum)
- Multiple frequency skew: 200ps (maximum)
- 3.3V core, 3.3V or 2.5V output supply modes
- -40°C to 85°C ambient operating temperature
- Lead-free packaging

Block Diagram



Pin Assignment



879461-147
32-Lead LQFP
7mm x 7mm x 1.4mm package body
Y Package
Top View

Pin Descriptions and Characteristics

Table 1. Pin Descriptions

| Number | Name | Type | | Description |
|---------------------------|--------------------|--------|----------|--|
| 1 | CLK_SEL | Input | Pulldown | Clock select input. When HIGH, selects CLK1. When LOW, selects CLK0. LVCMOS / LVTTTL interface levels. |
| 2 | V _{DD} | Power | | Positive supply pin. |
| 3, 4 | CLK0, CLK1 | Input | Pullup | Single-ended clock inputs. LVCMOS/LVTTTL interface levels. |
| 5 | DIV_SELA | Input | Pulldown | Controls frequency division for Bank A outputs. See Table 3 LVCMOS/LVTTTL interface levels. |
| 6 | DIV_SELB | Input | Pulldown | Controls frequency division for Bank B outputs. See Table 3. LVCMOS/LVTTTL interface levels. |
| 7 | DIV_SELCA | Input | Pulldown | Controls frequency division for Bank C outputs. See Table 3. LVCMOS/LVTTTL interface levels. |
| 8, 11, 15, 20, 24, 27, 31 | GND | Power | | Power supply ground. |
| 9, 13, 17 | V _{DDC} | Power | | Output supply pins for Bank C outputs. |
| 10, 12, 14, 16 | QC0, QC1, QC2, QC3 | Output | | Single-ended Bank C clock outputs. LVCMOS/LVTTTL interface levels. 7Ω typical output impedance. |
| 18, 22 | V _{ddb} | Power | | Output supply pins for Bank B outputs. |
| 19, 21, 23 | QB2, QB1, QB0 | Output | | Single-ended Bank B clock outputs. LVCMOS/LVTTTL interface levels. 7Ω typical output impedance. |
| 25, 29 | V _{DDA} | Power | | Output supply pins for Bank A outputs. |
| 26, 28, 30 | QA2, QA1, QA0 | Output | | Single-ended Bank A clock outputs. LVCMOS/LVTTTL interface levels. 7Ω typical output impedance. |
| 32 | MR/nOE | Input | Pulldown | Active HIGH Master Reset. Active LOW Output Enable. When logic HIGH, the internal dividers are reset and the outputs are (High-Impedance). When logic LOW, the internal dividers and the outputs are enabled. See Table 3. LVCMOS/LVTTTL interface levels. |

NOTE: *Pullup* and *Pulldown* refer to internal input resistors. See Table 2, *Pin Characteristics*, for typical values.

Table 2. Pin Characteristics

| Symbol | Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|-----------------------|-------------------------------|---|---------|---------|---------|-------|
| C _{IN} | Input Capacitance | | | | 4 | pF |
| C _{PD} | Power Dissipation Capacitance | V _{DD} = V _{DDA} = V _{ddb} = V _{DDC} = 3.6V | | 25 | | pF |
| R _{PULLUP} | Input Pullup Resistor | | | 51 | | kΩ |
| R _{PULLDOWN} | Input Pulldown Resistor | | | 51 | | kΩ |
| R _{OUT} | Output Impedance | | | 7 | | Ω |

Function Tables

Table 3. Clock Input Function Table

| Inputs | | | | Outputs | | |
|--------|----------|----------|-----------|----------------|----------------|----------------|
| MR/nOE | DIV_SELA | DIV_SELB | DIV_SEL C | QA0:QA2 | QB0:QB2 | QC0:QC3 |
| 1 | X | X | X | High-Impedance | High-Impedance | High-Impedance |
| 0 | 0 | X | X | $f_{IN}/1$ | Active | Active |
| 0 | 1 | X | X | $f_{IN}/2$ | Active | Active |
| 0 | X | 0 | X | Active | $f_{IN}/1$ | Active |
| 0 | X | 1 | X | Active | $f_{IN}/2$ | Active |
| 0 | X | X | 0 | Active | Active | $f_{IN}/1$ |
| 0 | X | X | 1 | Active | Active | $f_{IN}/2$ |

Absolute Maximum Ratings

NOTE: Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of the product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

| Item | Rating |
|--|---------------------------|
| Supply Voltage, V_{DD} | 4.6V |
| Inputs, V_I | -0.5V to $V_{DD} + 0.5V$ |
| Outputs, V_O | -0.5V to $V_{DDX} + 0.5V$ |
| Package Thermal Impedance, θ_{JA} | 47.9°C/W (0 lfpm) |
| Storage Temperature, T_{STG} | -65°C to 150°C |
| Junction Temperature | 125°C |

DC Electrical Characteristics

Table 4A. Power Supply DC Characteristics, $V_{DD} = V_{DDA} = V_{DDB} = V_{DDC} = 3.3V \pm 0.3V$, $T_A = -40^\circ C$ to $85^\circ C$

| Symbol | Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|-----------------------------------|-------------------------|-----------------|---------|---------|---------|-------|
| V_{DD} | Positive Supply Voltage | | 3.0 | 3.3 | 3.6 | V |
| V_{DDA} , V_{DDB} , V_{DDC} | Output Supply Voltage | | 3.0 | 3.3 | 3.6 | V |
| I_{DD} | Power Supply Current | | | | 55 | mA |
| I_{DDA} , I_{DDB} , I_{DDC} | Output Supply Current | | | | 23 | mA |

Table 4B. Power Supply DC Characteristics, $V_{DD} = 3.3V \pm 5\%$, $V_{DDA} = V_{DDB} = V_{DDC} = 2.5V \pm 5\%$, $T_A = -40^{\circ}C$ to $85^{\circ}C$

| Symbol | Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|-----------------------------------|-------------------------|-----------------|---------|---------|---------|-------|
| V_{DD} | Positive Supply Voltage | | 3.135 | 3.3 | 3.465 | V |
| V_{DDA} , V_{DDB} , V_{DDC} | Output Supply Voltage | | 2.375 | 2.5 | 2.625 | V |
| I_{DD} | Power Supply Current | | | | 55 | mA |
| I_{DDA} , I_{DDB} , I_{DDC} | Output Supply Current | | | | 22 | mA |

Table 4C. LVCMOS/LVTTL DC Characteristics, $V_{DD} = V_{DDA} = V_{DDB} = V_{DDC} = 3.3V \pm 0.3V$, $T_A = -40^{\circ}C$ to $85^{\circ}C$

| Symbol | Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|-----------|-----------------------------|---|---------|---------|----------------|---------|
| V_{IH} | Input High Voltage | | 2 | | $V_{DD} + 0.3$ | V |
| V_{IL} | Input Low Voltage | MR/nOE, DIV_SELA, DIV_SELB, DIV_SEL, CLK_SEL | -0.3 | | 0.8 | V |
| | | CLK0, CLK1 | -0.3 | | 1.3 | V |
| I_{IH} | Input High Current | MR/nOE, DIV_SELA, DIV_SELB, DIV_SEL, CLK_SEL $V_{DD} = V_{IN} = 3.6V$ | | | 150 | μA |
| | | CLK0, CLK1 $V_{DD} = V_{IN} = 3.6V$ | | | 5 | μA |
| I_{IL} | Input Low Current | MR/nOE, DIV_SELA, DIV_SELB, DIV_SEL, CLK_SEL $V_{DD} = 3.6V$, $V_{IN} = 0V$ | -5 | | | μA |
| | | CLK0, CLK1 $V_{DD} = 3.6V$, $V_{IN} = 0V$ | -150 | | | μA |
| V_{OH} | Output High Voltage; NOTE 1 | $V_{DDA} = V_{DDB} = V_{DDC} = 3.6V$ | 2.6 | | | V |
| V_{OL} | Output Low Voltage; NOTE 1 | $V_{DDA} = V_{DDB} = V_{DDC} = 3.63V$ | | | 0.5 | V |
| I_{OZL} | Output Hi-Z Current Low | $V_{DDA} = V_{DDB} = V_{DDC} = 3.63V$ | -5 | | | μA |
| I_{OZH} | Output Hi-Z Current High | $V_{DDA} = V_{DDB} = V_{DDC} = 3.63V$ | | | 5 | μA |

NOTE 1: Outputs terminated with 50Ω to $V_{DDx}/2$. See Parameter Measurement Information section. *Load Test Circuit diagrams.*

Table 4D. LVC MOS/LVTTL DC Characteristics, $V_{DD} = 3.3V \pm 5\%$, $V_{DDA} = V_{DDB} = V_{DDC} = 2.5V \pm 5\%$, $T_A = -40^\circ\text{C}$ to 85°C

| Symbol | Parameter | | Test Conditions | Minimum | Typical | Maximum | Units |
|-----------|-----------------------------|--|--|---------|---------|----------------|---------------|
| V_{IH} | Input High Voltage | | | 2 | | $V_{DD} + 0.3$ | V |
| V_{IL} | Input Low Voltage | MR/nOE, DIV_SELA, DIV_SELB, DIV_SEL, CLK_SEL | | -0.3 | | 0.8 | V |
| | | CLK0, CLK1 | | -0.3 | | 1.3 | V |
| I_{IH} | Input High Current | MR/nOE, DIV_SELA, DIV_SELB, DIV_SEL, CLK_SEL | $V_{DD} = V_{IN} = 3.465V$ | | | 150 | μA |
| | | CLK0, CLK1 | $V_{DD} = V_{IN} = 3.465V$ | | | 5 | μA |
| I_{IL} | Input Low Current | MR/nOE, DIV_SELA, DIV_SELB, DIV_SEL, CLK_SEL | $V_{DD} = 3.465V, V_{IN} = 0V$ | -5 | | | μA |
| | | CLK0, CLK1 | $V_{DD} = 3.465V, V_{IN} = 0V$ | -150 | | | μA |
| V_{OH} | Output High Voltage; NOTE 1 | | $V_{DDA} = V_{DDB} = V_{DDC} = 2.625V$ | 1.8 | | | V |
| V_{OL} | Output Low Voltage; NOTE 1 | | $V_{DDA} = V_{DDB} = V_{DDC} = 2.625V$ | | | 0.5 | V |
| I_{OZL} | Output Hi-Z Current Low | | $V_{DDA} = V_{DDB} = V_{DDC} = 2.625V$ | -5 | | | μA |
| I_{OZH} | Output Hi-Z Current High | | $V_{DDA} = V_{DDB} = V_{DDC} = 2.625V$ | | | 5 | μA |

NOTE 1: Outputs terminated with 50Ω to $V_{DDX}/2$. See Parameter Measurement Information section. *Load Test Circuit diagrams.*

AC Electrical Characteristics

Table 5A. AC Characteristics, $V_{DD} = V_{DDA} = V_{DDB} = V_{DDC} = 3.3V \pm 0.3V$, $T_A = -40^{\circ}C$ to $85^{\circ}C$

| Symbol | Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|--------------|---------------------------------------|--|--------------------|----------------|--------------------|-------|
| f_{MAX} | Output Frequency | | | | 250 | MHz |
| t_{PD} | Propagation Delay; NOTE 1 | $f \leq 250MHz$ | 2 | | 5 | ns |
| $t_{sk(b)}$ | Bank Skew, NOTE 2, 7 | Measured on rising edge at $V_{DDX}/2$ | | | 30 | ps |
| $t_{sk(o)}$ | Output Skew; NOTE 3, 7 | Measured on rising edge at $V_{DDX}/2$ | | | 175 | ps |
| $t_{sk(w)}$ | Multiple Frequency Skew; NOTE 4, 7 | Measured on rising edge at $V_{DDX}/2$ | | | 275 | ps |
| $t_{sk(pp)}$ | Part-to-Part Skew; NOTE 5, 7 | Measured on rising edge at $V_{DDX}/2$ | | | 850 | ps |
| t_R / t_F | Output Rise/Fall Time; NOTE 6 | 20% to 80% | 400 | | 950 | ps |
| t_{PW} | Output Pulse Width | | $t_{PERIOD}/2 - 1$ | $t_{PERIOD}/2$ | $t_{PERIOD}/2 + 1$ | % |
| t_{EN} | Output Enable Time; NOTE 6 | $f = 10MHz$ | | | 3 | ns |
| t_{DIS} | Output Disable Time; NOTE 6 | $f = 10MHz$ | | | 3 | ns |

NOTE: Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

NOTE 1: Measured from $V_{DD}/2$ of the input to $V_{DDX}/2$ of the output.

NOTE 2: Defined as skew within a bank of outputs at the same supply voltage and with equal load conditions.

NOTE 3: Defined as skew across banks of outputs at the same supply voltage and with equal load conditions. Measured at $V_{DDX}/2$.

NOTE 4: Defined as skew across banks of outputs operating at different frequencies with the same supply voltage and equal load conditions.

NOTE 5: Defined as skew between outputs on different devices operating at the same supply voltage and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at $V_{DDX}/2$.

NOTE 6: These parameters are guaranteed by characterization. Not tested in production.

NOTE 7: This parameter is defined in accordance with JEDEC Standard 65.

Table 5B. AC Characteristics, $V_{DD} = 3.3V \pm 5\%$, $V_{DDA} = V_{DDB} = V_{DDC} = 2.5V \pm 5\%$, $T_A = -40^\circ\text{C}$ to 85°C

| Symbol | Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|--------------|---------------------------------------|--|--------------------|----------------|--------------------|-------|
| f_{MAX} | Output Frequency | | | | 250 | MHz |
| t_{PD} | Propagation Delay; NOTE 1 | $f \leq 250\text{MHz}$ | 2 | | 5 | ns |
| $t_{sk(b)}$ | Bank Skew, NOTE 2, 7 | Measured on rising edge at $V_{DDX}/2$ | | | 35 | ps |
| $t_{sk(o)}$ | Output Skew; NOTE 3, 7 | Measured on rising edge at $V_{DDX}/2$ | | | 175 | ps |
| $t_{sk(w)}$ | Multiple Frequency Skew; NOTE 4, 7 | Measured on rising edge at $V_{DDX}/2$ | | | 200 | ps |
| $t_{sk(pp)}$ | Part-to-Part Skew; NOTE 5, 7 | Measured on rising edge at $V_{DDX}/2$ | | | 875 | ps |
| t_R / t_F | Output Rise/Fall Time; NOTE 6 | 20% to 80% | 400 | | 950 | ps |
| t_{PW} | Output Pulse Width | | $t_{PERIOD}/2 - 1$ | $t_{PERIOD}/2$ | $t_{PERIOD}/2 + 1$ | % |
| t_{EN} | Output Enable Time; NOTE 6 | $f = 10\text{MHz}$ | | | 3 | ns |
| t_{DIS} | Output Disable Time; NOTE 6 | $f = 10\text{MHz}$ | | | 3 | ns |

NOTE: Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

NOTE 1: Measured from $V_{DD}/2$ of the input to $V_{DDX}/2$ of the output.

NOTE 2: Defined as skew within a bank of outputs at the same supply voltage and with equal load conditions.

NOTE 3: Defined as skew across banks of outputs at the same supply voltage and with equal load conditions. Measured at $V_{DDX}/2$.

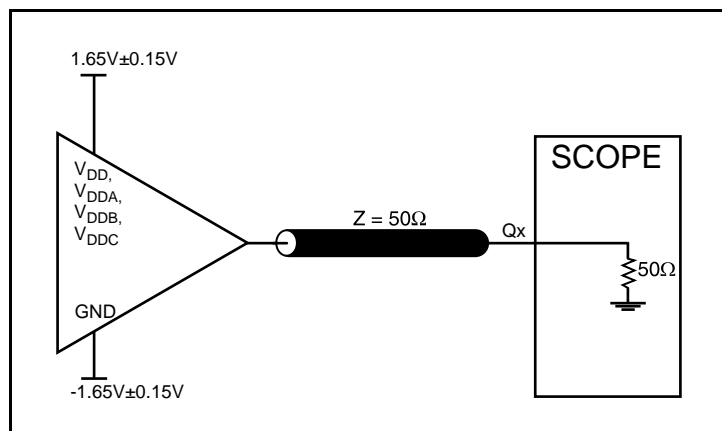
NOTE 4: Defined as skew across banks of outputs operating at different frequencies with the same supply voltage and equal load conditions.

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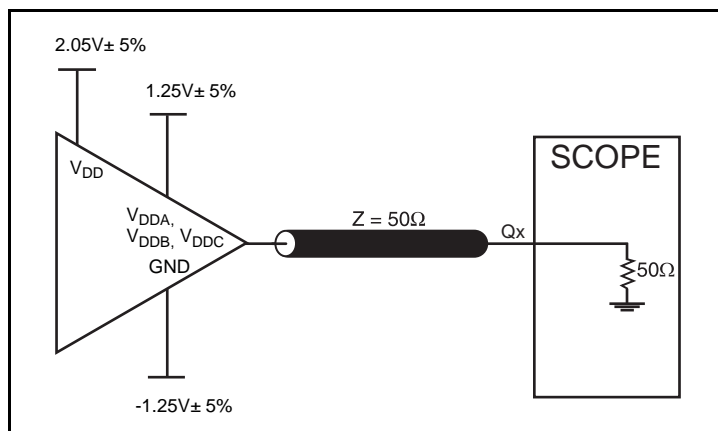
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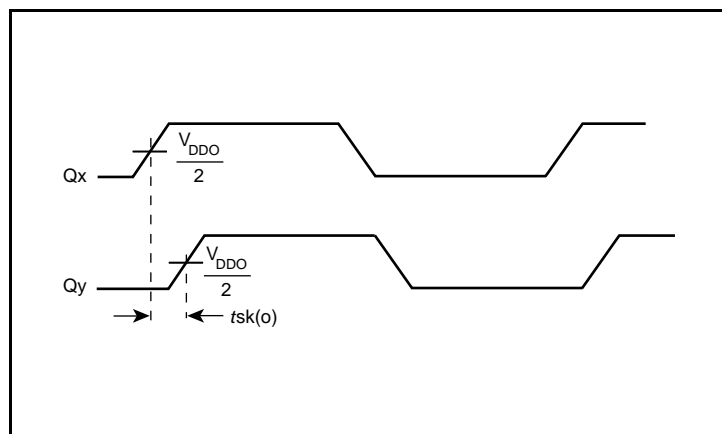
Parameter Measurement Information



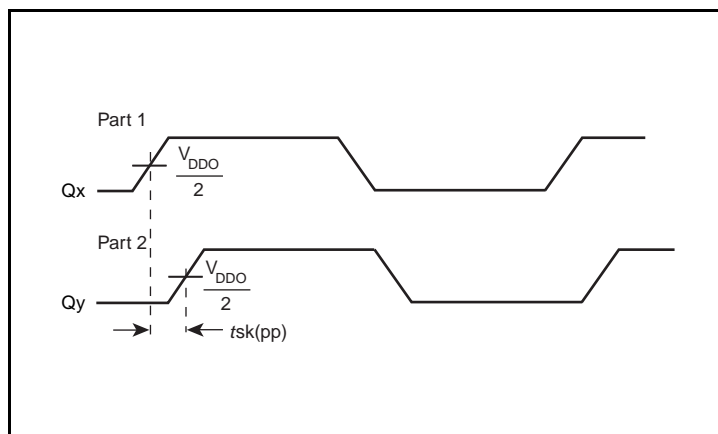
3.3V Core/3.3V Output Load AC Test Circuit



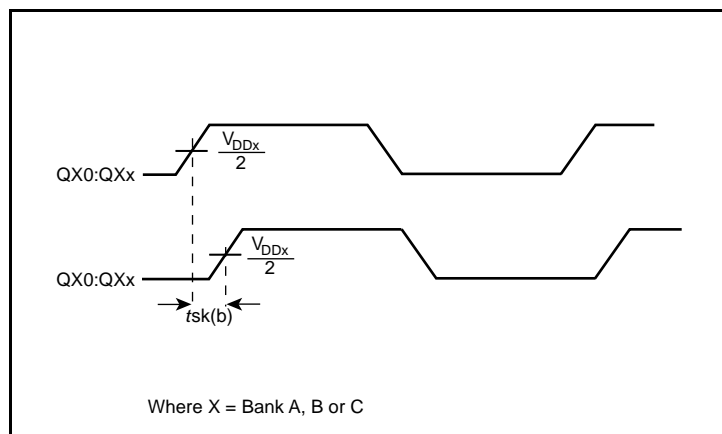
3.3V Core/2.5V Output Load AC Test Circuit



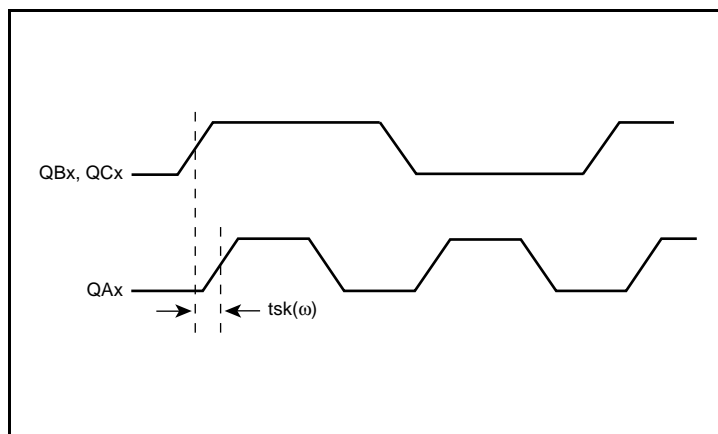
Output Skew



Part-to-Part Skew

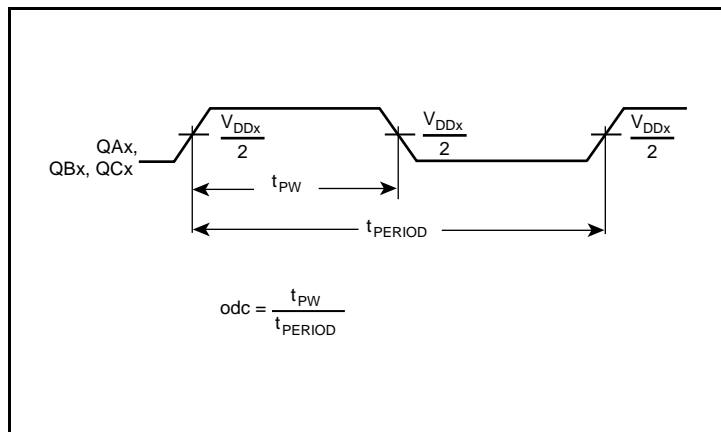


Bank Skew

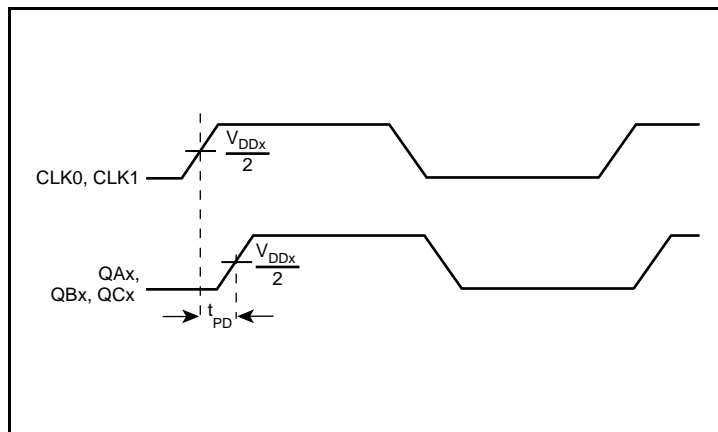


Multiple Frequency Skew

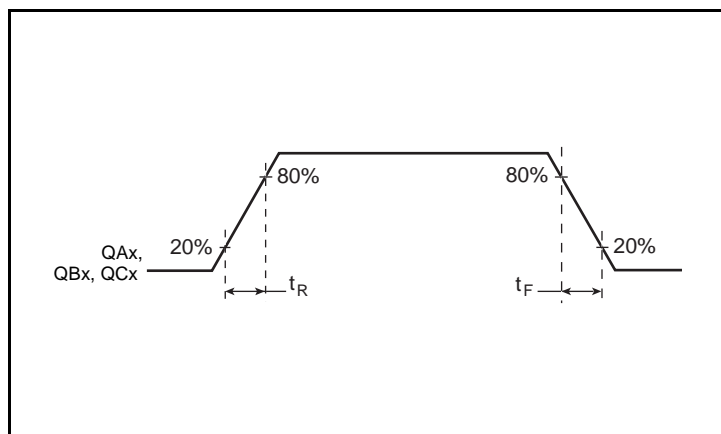
Parameter Measurement Information, continued



t_{PW} & t_{PERIOD}



Propagation Delay



Output Rise/Fall Time

Applications Information

Recommendations for Unused Input and Output Pins

Inputs:

LVC MOS Control Pins

All control pins have internal pulldowns; additional resistance is not required but can be added for additional protection. A 1k Ω resistor can be used.

CLK Inputs

For applications not requiring the use of a clock input, it can be left floating. Though not required, but for additional protection, a 1k Ω resistor can be tied from the CLK input to ground.

Outputs:

LVC MOS Outputs

All unused LVC MOS output can be left floating. There should be no trace attached.

Reliability Information

Table 6. θ_{JA} vs. Air Flow Table for a 32-Lead LQFP

| θ_{JA} vs. Air Flow | | | |
|--|----------|----------|----------|
| Linear Feet per Minute | 0 | 200 | 500 |
| Single-Layer PCB, JEDEC Standard Test Boards | 67.8°C/W | 55.9°C/W | 50.1°C/W |
| Multi-Layer PCB, JEDEC Standard Test Boards | 47.9°C/W | 42.1°C/W | 39.4°C/W |
| NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs. | | | |

Transistor Count

The transistor count for 87946I-147 is: 1204
Pin compatible to the MPC9446 and MPC946

Package Outline and Package Dimensions

Package Outline - Y Suffix for 32-Lead LQFP

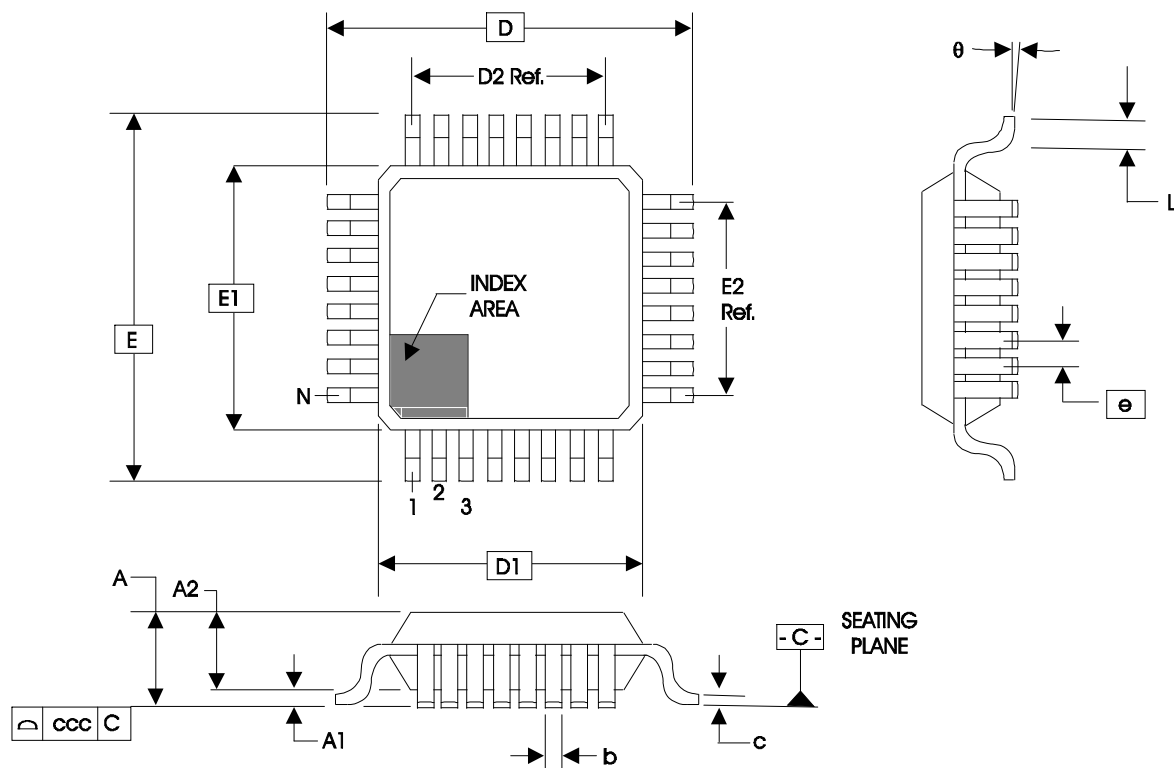


Table 7. Package Dimensions for 32-Lead LQFP

| JEDEC Variation: BBC - HD All Dimensions in Millimeters | | | |
|--|------------|---------|---------|
| Symbol | Minimum | Nominal | Maximum |
| N | 32 | | |
| A | | | 1.60 |
| A1 | 0.05 | 0.10 | 0.15 |
| A2 | 1.35 | 1.40 | 1.45 |
| b | 0.30 | 0.37 | 0.45 |
| c | 0.09 | | 0.20 |
| D & E | 9.00 Basic | | |
| D1 & E1 | 7.00 Basic | | |
| D2 & E2 | 5.60 Ref. | | |
| e | 0.80 Basic | | |
| L | 0.45 | 0.60 | 0.75 |
| θ | 0° | | 7° |
| ccc | | | 0.10 |

Reference Document: JEDEC Publication 95, MS-026

Ordering Information

Table 8. Ordering Information

| Part/Order Number | Marking | Package | Shipping Packaging | Temperature |
|-------------------|---------------|--------------------------|---|---------------|
| 87946AYI-147LF | ICS7946AI147L | "Lead-Free" 32-Lead LQFP | Tray | -40°C to 85°C |
| 87946AYI-147LFT | ICS7946AI147L | "Lead-Free" 32-Lead LQFP | Tape & Reel | -40°C to 85°C |
| 87946AYI-147LF/W | ICS7946AI147L | "Lead-Free" 32-Lead LQFP | Tape & Reel, Pin1 Orientation: EIA-481-D | -40°C to 85°C |

Revision History Sheet

| Rev | Table | Page | Description of Change | Date |
|-----|-----------------|-------|--|----------|
| A | T2 | 1 | Features section added <i>Lead-Free</i> bullet. | 7/22/08 |
| | | 2 | Pin Description Table - corrected description for V_{DDA} , V_{DDB} and V_{DDC} . | |
| | | 8 | Parameter Measurement Information Section - added part-to-part skew, bank skew, and multiple frequency skew diagrams. | |
| | T8 | 10 | Application Section - added <i>Recommendations for Unused Input and Output Pins</i> . | |
| | | 12 | Ordering Information Table - added lead-free marking. Updated format throughout the datasheet. | |
| A | T5A - T5B T8 | 6 - 7 | AC Tables - added thermal note. | 8/7/09 |
| | | 12 | Ordering Information Table - corrected the Part/Order Numbers and corrected the non-LF marking. Updated Header/Footer of the datasheet. | |
| A | T8 | 12 | Removed leaded orderable parts from Ordering Information table | 11/15/12 |
| A | T8 | 12 | Ordering Information Table - Added 87946AYI-147LF/W Ordering option. | 4/30/14 |
| | | 14 | Updated Technical Support Contact Info to: clocks@idt.com | |
| B | | 3 | Absolute Maximum Ratings Table - added Junction Temperature. Updated datasheet header/footer. Deleted "ICS" prefix from part number. | 2/24/16 |
| C | | 1 | Corrected datasheet title. Corrected <i>General Description</i> , first sentence from <i>Clock Generator</i> to <i>Fanout Buffer</i> . | |

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